Silicon N-Channel Power MOS FET Module

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Application

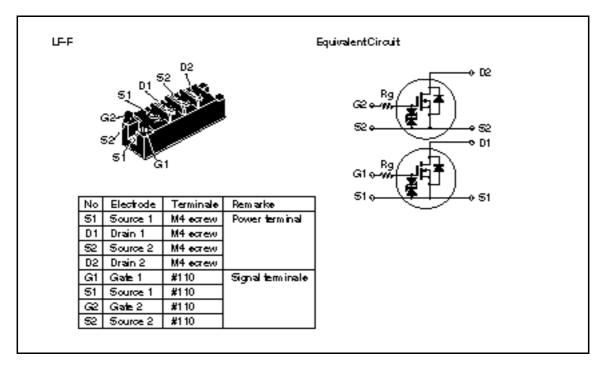
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- High speed switching
- Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

Item	Symbol	Rating	Unit
Drain source voltage	V _{DSS}	500	V
Gate source voltage	V _{GSS}	±20	V
Drain current	I _D	30	А
Drain peak current	l _{D(peak)}	60	А
Body to drain diode reverse drain current	I _{DR}	30	А
Body to drain diode reverse drain peak current	DR(peak)	60	А
Channel dissipation	Pch*1	200	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-45 to +125	°C
Insulation dielectric	Visol*2	2000	V
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Notes: 1. Value at Tc = 25°C

2. Base to terminals AC minute

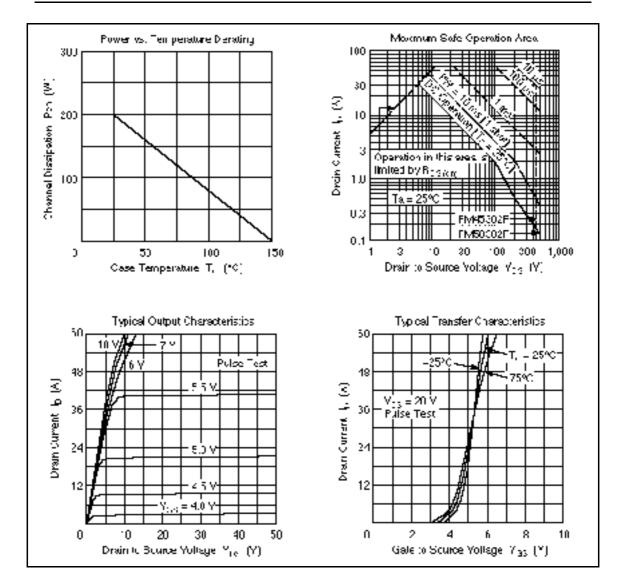
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	500	_	_	V	$I_{\rm D}$ = 10 mA, $V_{\rm GS}$ = 0
Gate to source leak current	I _{GSS}	_	_	±50	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±20	—	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		—	1	mA	$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	1.5	_	4.0	V	$I_{\rm D}$ = 1 mA, $V_{\rm DS}$ = 10 V
Drain to source saturation voltage	$V_{\text{DS(on)}}$	—	2.25	3.0	V	$I_{\rm D}$ = 15 A, $V_{\rm GS}$ = 10 V* ¹
Static Drain to source on state resistance	$R_{\text{DS(on)}}$	—	0.15	0.20		$I_{\rm D}$ = 15 A, $V_{\rm GS}$ = 10 V* ¹
Forward transfer admittance	y _{fs}	15	25		S	$I_{\rm D} = 15 \text{ A}, V_{\rm DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	6150		pF	$V_{\rm DS} = 10 \ V, \ V_{\rm GS} = 0 \ V$
Output capacitance	Coss	_	2160		pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	240		pF	_
Turn-on delay time	t _{d(on)}		100		ns	$I_{\rm D} = 15$ A, $V_{\rm GS} = 10$ V
Rise time	t _r	_	480	_	ns	$R_L = 2$
Turn-off delay time	$t_{d(off)}$		500	_	ns	_
Fall time	t _f	_	400	_	ns	_
Body to drain diode forward voltage	V_{DF}	—	1.2	—	V	$I_{F} = 15 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		200	_	ns	I _F = 15 A, V _{GS} = 0 diF/dt = 100 A/μs

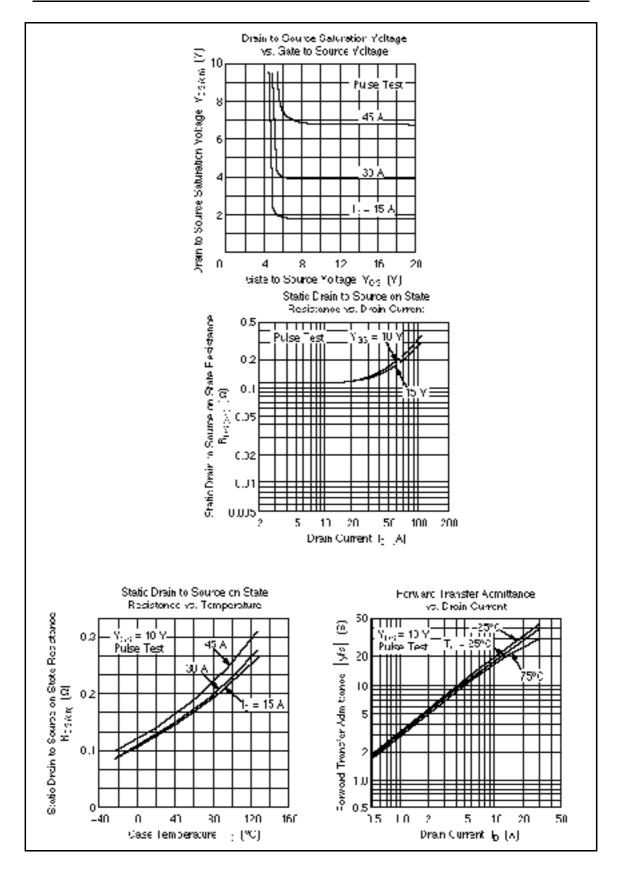
Electrical Characteristics (Ta = 25°C) (Per FET chip)

Note: 1. Pulse Test

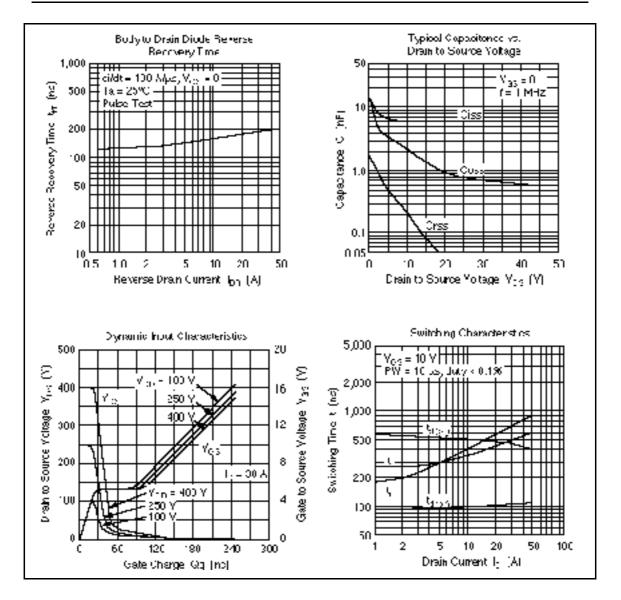
Mechanical Characteristics

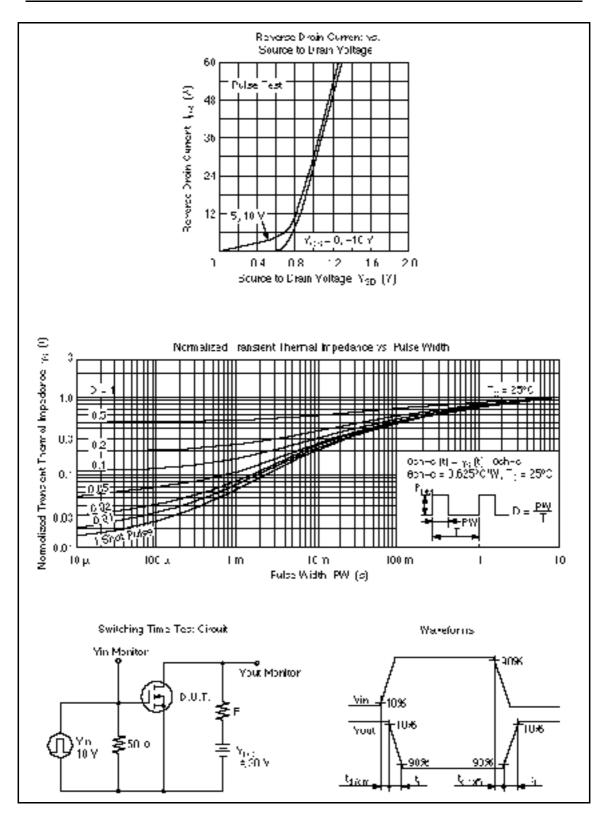
Symbol	Condition	Rating	Unit
_	Mounting into main-terminal with M4 screw	15 to 20	kg•cm
_	Mounting into heat sink with M5 screw	15 to 25	kg∙cm
_	Typical value	220	g
	Symbol 	 Mounting into main-terminal with M4 screw Mounting into heat sink with M5 screw 	— Mounting into main-terminal with M4 screw 15 to 20 — Mounting into heat sink with M5 screw 15 to 25





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